Abstracts

A Two-Tier Deembedding Technique for Packaged Transistors

R. Vaitkus and D. Scheitlin. "A Two-Tier Deembedding Technique for Packaged Transistors." 1982 MTT-S International Microwave Symposium Digest 82.1 (1982 [MWSYM]): 328-330.

This paper describes a technique for deembedding transistor chip scattering parameters from the measurements of packaged devices in a standard transistor test fixture by the use of a set of secondary calibration standards, consisting of empty and specially wire-bonded transistor packages.

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